



**Product Model 6497:**  
For MCM/Hybrid/Silver Glass/Eutectic and Flip Chip

**MAT – MicroAssembly Technologies, Ltd.**  
**Product Model 6497**

Performs Flip Chip, MCM/Hybrid/COB, Silver Glass, Eutectic, Ultrasonic processes.

Table top design including high accuracy features required for state of the art flip chip or chip and wire applications.

Full software control, with programmable process parameters such as Forces, Velocities, times, dispensing, Bond Line Thickness, Scrubbing, Ultrasonic, Vision, etc.

Pick from 2" or 4" Waffle or Gel-Pak.

Cold as well as high temperature processes under inert gas cover.

High Accuracy and Yield.

Ideal for low to medium volume production.

